

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

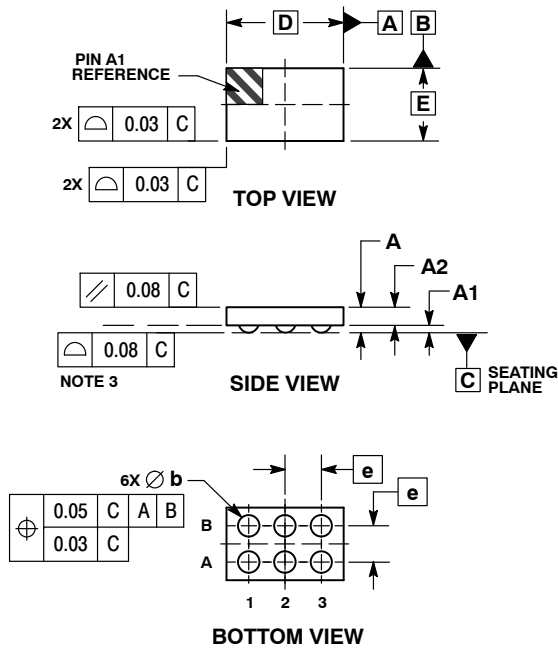
ON Semiconductor®



SCALE 4:1

WLCSP6, 1.29x0.80  
CASE 567GL  
ISSUE O

DATE 23 JAN 2013

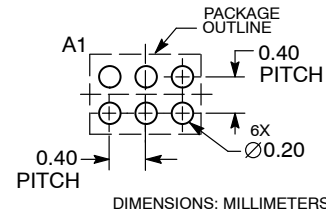


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.33
A1	0.03	0.13
A2	0.20 REF	
b	0.15	0.25
D	1.29 BSC	
E	0.80 BSC	
e	0.40 BSC	

**RECOMMENDED  
SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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